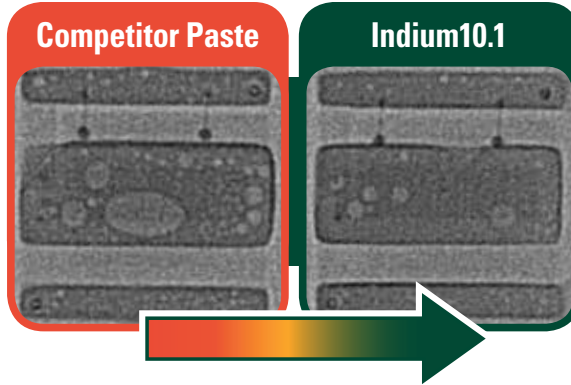
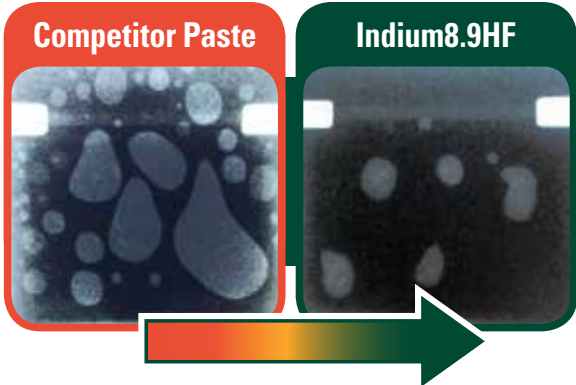




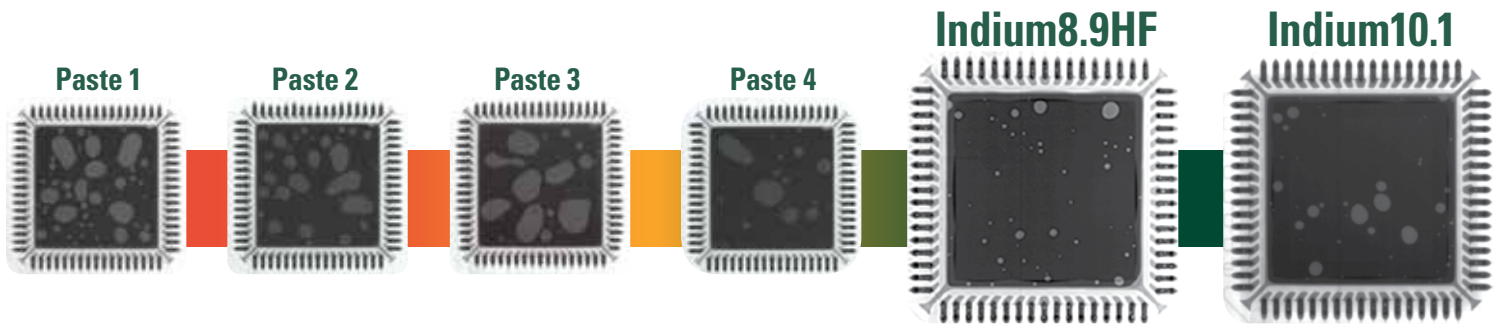
Indium8.9HF and Indium10.1 Solder Pastes

Halogen-Free, No-Clean

No-Clean, Pb-Free
Lowest Voiding Performance

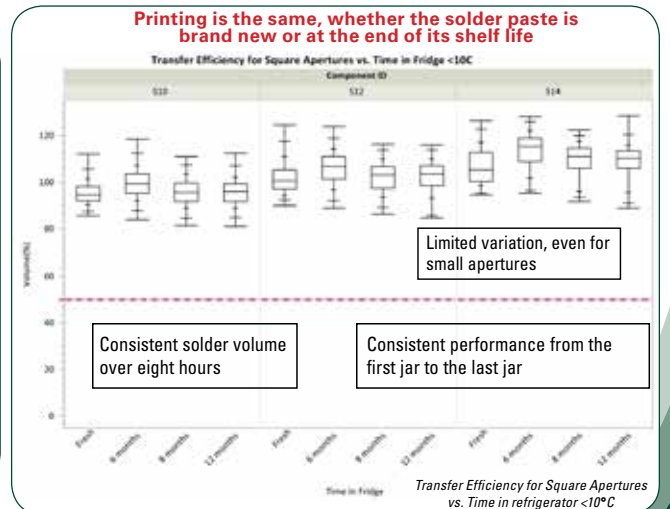
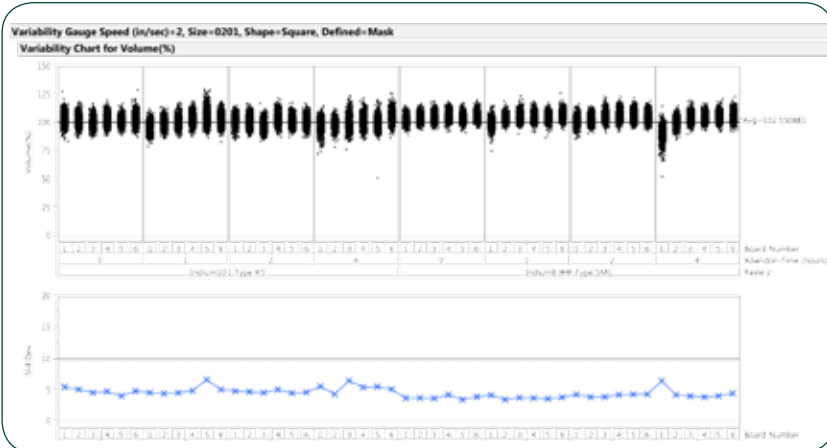


CUSTOMER EXPERIENCE:
From >40% voiding down to <15% by switching to Indium8.9HF and >30% voiding down to <15% by switching to Indium10.1



Excellent Response-to-Pause Print Performance
Type 3, 4, 4.5 & 5-MC

Room Temperature Stable (Indium8.9HF & Indium10.1)



Industry-Leading Head-in-Pillow Performance



From One Engineer To Another®

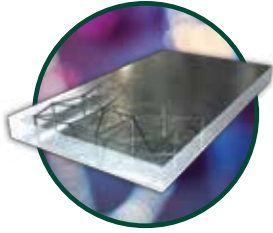
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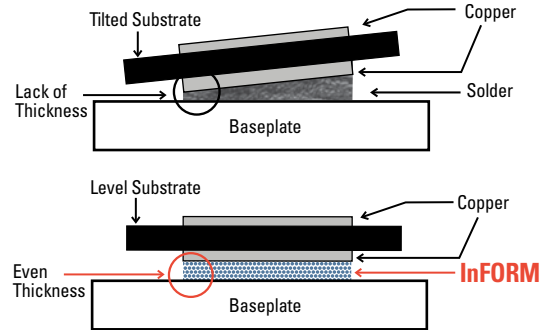


Engineered Solders



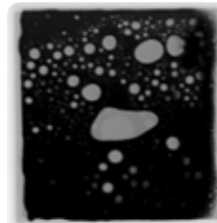
InFORMS®

- >2X increase in reliability (-55/+150°C); passes 3,500 thermal cycles
- Eliminates costly wire bond trimming process
- Most uniform bondline control



LV1000 Flux-Coated Preforms

- Meets tightest tolerances for flatness; reduces open joints
- Durable, uniform coating
- Tape & reel packaging for automated assembly



Typical Poor Voiding
10-12% Void Area

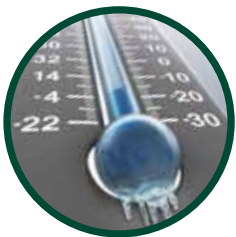
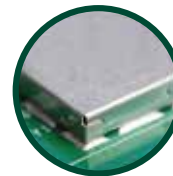


LV1000
<2% Void Area



Solder Fortification® Preforms

- Additional solder volume for improved reliability
- Reduces QFN voiding
- Wide array of sizes
- Packaged in tape & reel



Low-Temperature Solders (115°C to 190°C)

Common Applications:

- Temperature-sensitive components
- Substrates that deform, melt, or delaminate at higher reflow temperatures
- Step-soldering
- CTE mismatch

Solder Forms:

- Paste
- Preforms
- Solid Wire
- Spheres
- Ribbon/Foil

Contact our engineers today: askus@indium.com

Learn more: www.indium.com

From One Engineer To Another®

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